

Dimension Chip Size

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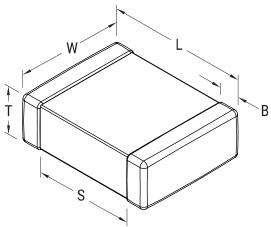
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В

## C1210X249D2TACTU

Aliases (C1210X249D2TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 2.4 pF, +/-0.5 pF, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



S		AEC-Q200
		Typical Component
Click here for the	the 3D model.	Shelf Life
		MSL
ns		Specifications
ns	1210	Specifications Capacitance
ns	1210 3.3mm +/-0.4mm	
ns		Capacitance

0.78mm +/-0.20mm

0.6mm +/-0.25mm

1.5mm MIN

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	30 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	2.4 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	+/-0.5 pF
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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